

# SOT941-1

plastic thermal enhanced very thin quad flat package; no leads; 112 terminals; body 7 x 7 x 0.9 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN112U
<b>Package type industry code</b>	HVQFN112U
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	1	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.9	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	112	-	



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## 2. Package outline

HVQFN112U: plastic thermal enhanced very thin quad flat package; no leads; 112 terminals; UTLP based; body 7 x 7 x 0.9 mm

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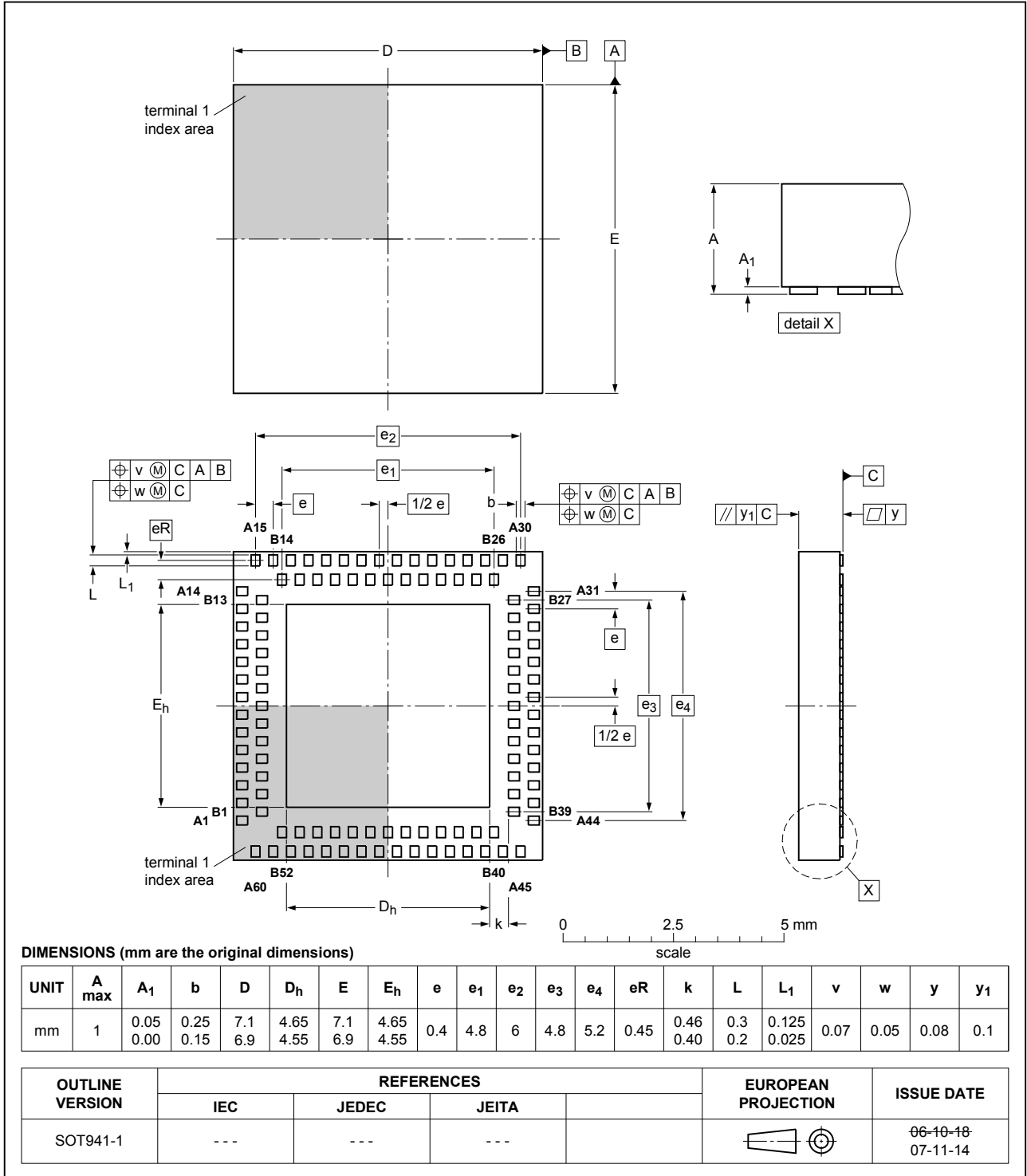


Fig. 1. Package outline HVQFN112U (SOT941-1)

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### 3. Legal information

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Date of release: 8 February 2016

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